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**Fibre optic interconnecting devices and passive components – Basic test and measurement procedures –
Part 3-44: Examinations and measurements – Fibre optic transceiver receptacle endface visual and automated inspection**

**Dispositifs d'interconnexion et composants passifs à fibres optiques –
Méthodes fondamentales d'essais et de mesures –
Partie 3-44: Examens et mesures – Inspection automatique et visuelle de
l'extrémité des embases d'émetteurs-récepteurs à fibres optiques**



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INTERNATIONAL ELECTROTECHNICAL COMMISSION

**FIBRE OPTIC INTERCONNECTING
DEVICES AND PASSIVE COMPONENTS –
BASIC TEST AND MEASUREMENT PROCEDURES –**

**Part 3-44: Examinations and measurements –
Fibre optic transceiver receptacle endface
visual and automated inspection**

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International Standard IEC 61300-3-44 has been prepared by subcommittee 86B: Fibre optic interconnecting devices and passive components, of IEC technical committee 86: Fibre optics.

The text of this standard is based on the following documents:

FDIS	Report on voting
86B/3424/FDIS	86B/3467/RVD

Full information on the voting for the approval of this standard can be found in the report on voting indicated in the above table.

This publication has been drafted in accordance with the ISO/IEC Directives, Part 2.

A list of all parts of IEC 61300 series, published under the general title *Fibre optic interconnecting devices and passive components – Basic test and measurement procedures*, can be found on the IEC website.

The committee has decided that the contents of this publication will remain unchanged until the stability date indicated on the IEC web site under "<http://webstore.iec.ch>" in the data related to the specific publication. At this date, the publication will be

- reconfirmed,
- withdrawn,
- replaced by a revised edition, or
- amended.

This document is withdrawn when IEC 61300-3-35 Edition 2.0 is published.

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FIBRE OPTIC INTERCONNECTING DEVICES AND PASSIVE COMPONENTS – BASIC TEST AND MEASUREMENT PROCEDURES –

Part 3-44: Examinations and measurements – Fibre optic transceiver receptacle endface visual and automated inspection

1 Scope

This part of IEC 61300 describes methods for quantitatively assessing the endface quality of an optic receptacle interface for single mode applications, equipped with transceivers such as SFP/XFP. Lens type and stub ferrule type interface configurations are designed for this interface, but this standard defines the end face quality of the stub ferrule type in this edition. The information is intended for use with other standards which set requirements for allowable surface defects such as scratches, pits and debris which may affect optical performance. In general, the methods described in this standard apply to 125 μm cladding fibres contained within a ferrule and intended for use with sources of $\leq 2\text{ W}$ of input power.

2 Measurement

2.1 General

The objective of this document is to prescribe methods for quantitatively inspecting fibre optic endfaces to determine if they are suitable for use. Two methods are described: A: video microscopy and B: automated analysis microscopy. Within each method, there are hardware requirements and procedures for both low resolution and high resolution systems. High resolution systems are to be utilized for critical examination of the glass fibre after polishing and upon incoming quality assurance. High resolution systems are typically not used during field polishing or in conjunction with multimode connectors. Low resolution systems are to be utilized prior to mating connectors for any purpose. All methods require a means for measuring and quantifying defects.

There are many types of defects. Commonly used terminology would include: particles, pits, chips, scratches, embedded debris, loose debris, cracks, etc. For practical purposes, all defects will be categorized in one of two groups. They are defined as follows:

scratches: permanent linear surface features;

defects: all non-linear features detectable on the fibre. This includes particulates, other debris, pits, chips, edge chipping, etc.

All defects and scratches are surface anomalies. Sub-surface cracks and fractures are not reliably detectable with a light microscope in all situations and are therefore not covered within this standard. Cracks and fractures to the fibre may be detected with a light microscope and are generally considered a catastrophic failure.

Differentiating between a scratch and all other defects is generally intuitive to a human being. However, to provide clarity, and for automated systems, scratches are defined as being less than 4 μm wide, linear in nature, and with a length that is at least 30 times their width. As the width dimension is not practical to measure below 3 μm , these figures can be grossly estimated.

Defects size is defined for method A as the diameter of the smallest circle that can encompass the entire defect. Defect size for method B can be either the actual measured surface area or

the diameter of the smallest circle than can encompass the entire defect. For the purposes of this standard the smallest circle method shall be used.

For method A, it is recommended that visual gauge tools be developed to facilitate the measurement procedure. In addition, an overlay is recommended.

2.2 Measurement conditions

No restrictions are placed on the range of atmospheric conditions under which the test can be conducted. It may be performed in controlled or uncontrolled environments

2.3 Pre-conditioning

No minimum pre-conditioning time is required.

2.4 Recovery

Since measurements are to be made at standard test conditions, no minimum recovery time is required.

3 Apparatus

3.1 Method A: video microscopy

This method utilizes a light microscope in which a lens system forms an image on a sensor which, in turn, transfers the image to a display. The user views the image on the display. It shall have the following features and capabilities:

- a suitable ferrule or connector adapter;
- a light source and focusing mechanism;
- a means to measure defects observed in the image.

3.2 Method B: automated analysis microscopy

This method utilizes a light microscope in which a digital image is acquired or created and subsequently analyzed via an algorithmic process. The purpose of such a system is to reduce the effects of human subjectivity in the analysis process and, in some cases, to improve cycle times. It shall have the following features and capabilities:

- a suitable ferrule or connector adapter;
- a means for acquiring or creating a digital image;
- algorithmic analysis of the digital image.

A means to compare the analyzed image to programmable acceptance criteria in such a manner that a result of “pass” or “fail” is provided.

3.3 Calibration requirements for low and high resolution systems

3.3.1 General

Microscope systems for any of the methods above shall be calibrated for use in either low or high resolution applications. It is suggested that this calibration be conducted with a purpose-built calibration artefact that can serve to validate a system's ability to detect defects of relevant size. Such an artefact shall be provided with instructions on its use and shall be manufactured by a method such that it can be measured in a traceable manner. Details on the manufacture of such artefacts can be found in Annex A.

For reference, a system's optical resolution may be calculated using the formula below. Optical resolution is not equivalent to the system's detection capability. In most cases, the system will be able to detect defects smaller than its optical resolution.

Optical resolution = $(0,61 \times \text{Wavelength of illumination source}) / \text{system's numerical aperture}$

3.3.2 Requirements for low resolution microscope systems

Minimum total magnification offering a field of view of at least 250 μm (for methods A and B, this dimension is to be measured in the vertical, or most constrained, axis) capable of detecting low-contrast defects of 2 μm in diameter or width.

3.3.3 Requirements for high resolution microscope systems

Minimum total magnification offering a field of view of at least 120 μm (for methods A and B, this dimension shall be measured in the vertical, or most constrained, axis) capable of detecting low contrast scratches of 0,2 μm in width and 0,003 μm in depth.

4 Procedure

4.1 Measurement regions

For the purposes of setting requirements on endface quality, the polished endface of a receptacle interface is divided into measurement regions. These regions are concentric with the fibre OD and are defined in Table 1. If a defect is found to be in more than one zone, it shall be counted in all zones it touches.

Table 1 – Measurement regions

Zone	Diameter
A: core	0 μm to 15 μm
B: cladding	15 μm to 115 μm
C: adhesive	115 μm to 135 μm
D: contact	135 μm to 250 μm
NOTE 1 Data above assumes a 125 μm cladding diameter.	

4.2 Calibration procedure

On commissioning, and periodically during its life, the microscope system shall be calibrated.

Fix the artefact(s) on the microscope system, focus the image.

Follow manufacturer's instructions on how to calibrate the system using the artefact. Generally, this should entail viewing the artefact and verifying that the small features and contrast targets are "reliably detectable"; and that the region of interest can be fully viewed or scanned. "Reliably detectable" is defined as sufficiently clear and visible so that a typical technician of average training would recognize the feature at least 98 % of the time.

For automated systems, software utilities to perform this calibration shall be provided. In any event, those systems shall be able to perform the same calibration to validate that they can reliably detect the features of the artefact.

4.3 Inspection procedure

Focus the microscope so that a crisp image can be seen.

Locate all defects and scratches within the zones prescribed in the acceptance criteria. Count and measure defects and count scratches within each zone. Scratches that are extremely wide may be judged to be too large per the acceptance criteria and result in immediate failure of the DUT.

Once all defects and scratches have been quantified, the results should be totalled by zone and compared to the appropriate acceptance criteria. Such criteria can be found in 5.4.

Any endface with quantified defects or scratches in excess of the values shown in any given zone on the table are determined to have failed.

If the fibre fails inspection for defects, the user shall clean the fibre and repeat the inspection process. In this way, loose debris can be removed and the fibre may be able to pass a subsequent inspection without rework or scrap. Cleaning shall be repeated a number of times consistent with the cleaning procedure being used.

Figure 1 shows the inspection procedure flow.

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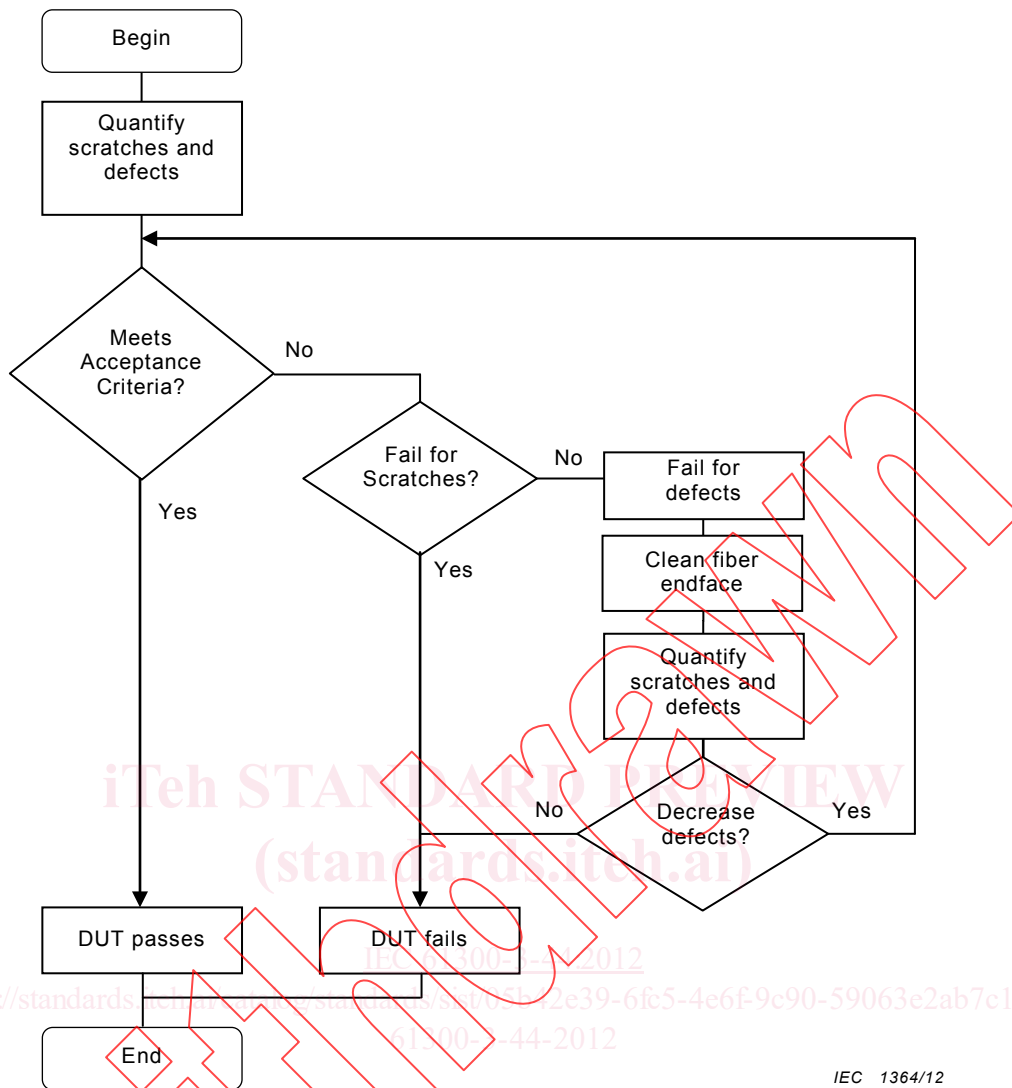


Figure 1 – Inspection procedure flow

4.4 Visual Requirements

Visual requirements are shown in Table 2.

Table 2 – Visual requirements for fibre receptacle interface equipped with transceivers

Zone name (diameter)	Scratches	Defects
A: core 0µm to 15 µm	2 ≤ 3 µm None > 3 µm	None
B: cladding 15µm to 115 µm	No limit ≤ 3 µm 3 > 3 µm	No limit ≤ 5µm 3 from 5µm to 10 µm None > 10 µm
C: adhesive 115µm to 135 µm	No limit	No limit
D: contact 135µm to 250 µm	No limit	No limit ≤ 20µm 3 from 20µm to 30µm None > 30 µm
<p>NOTE 1 For scratches, the requirement refers to width.</p> <p>NOTE 2 No visible subsurface cracks are allowed in the core or cladding zones.</p> <p>NOTE 3 All loose particles must be removed. If defect(s) are non-removable, it must be within the criteria above to be acceptable for use.</p> <p>NOTE 4 There are no requirements for the area outside the contact zone since defects in this area have no influence on the performance. Cleaning loose debris beyond this region is recommended good practice.</p> <p>NOTE 5 Criteria should be applied to all fibre pairs in the array for functionality of any fibre pairs in the array.</p> <p>NOTE 6 Structural features that are part of the functional design of the optical fibre, such as microstructures, are not considered defects.</p>		